

## ABSTRACT OF THE DISCLOSURE

### CLEANING FORMULATIONS

The present invention relates to an aqueous cleaning composition used to remove unwanted organic and inorganic residues and contaminants from semiconductor substrates. The cleaning composition comprises a urea derivative such as, for example, dimethyl urea, as the component that is principally responsible for removing organic residues from the substrate. A fluoride ion source is also included in the cleaning compositions of the present invention and is principally responsible for removing inorganic residues from the substrate. The cleaning compositions of the present invention have a low toxicity and are environmentally acceptable.

Fig.1